

# N-Channel Enhancement Mode MOSFET

## 1. Product Information

### Features

- Advanced SGT Technology
- Excellent  $R_{DS(ON)}$  and Switching Performance

### Applications

- DC/DC Converter
- LED Backlighting
- Power Management Switches

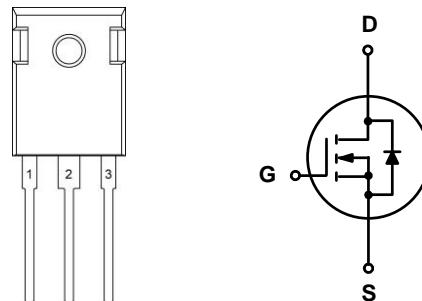
### Quick reference

$V_{DS} = 150V$   
 $I_D = 200A$   
 $R_{DS(ON)} \leq 7.2m\Omega$  @  $V_{GS}=10V$  (Type: 6.2 mΩ)

### Pin Description

Pin	Description
1	Gate(G)
2	Drain(D)
3	Source(S)

### Simplified Outline



Top View  
TO-247-3L

### Package Marking and Ordering Information

Product Name	Package	Marking		Reel Size	Tape Width	Quantity
KJ200N15P	TO-247-3L	200N15	XXXXYY: Date Code	-	-	300

## 2. Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Values	Unit
$V_{DS}$	Drain-Source Voltage	150	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c=25^\circ C$	Continuous Drain Current, $V_{GS}@10V$	200	A
$I_D @ T_c=100^\circ C$	Continuous Drain Current, $V_{GS}@10V$	140	A
$I_{DM}$	Pulsed Drain Current	550	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>3</sup>	506	mJ
$I_{AS}$	Avalanche Current	53.4	A
$P_D @ T_c=25^\circ C$	Power Dissipation <sup>4</sup>	210	W
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55~150	°C
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	0.84	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case	40	°C/W

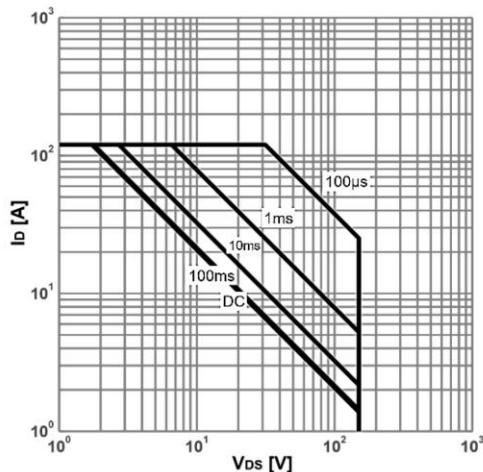
### 3. Electrical Characteristics ( $T_C=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu\text{A}$	150	-	-	V
$I_{GSS}$	Gate-body Leakage current	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	$\pm 100$	nA
$I_{DSS}$	Zero Gate Voltage Drain Current, $T_J=25^\circ\text{C}$	$V_{DS}=100V, V_{GS}=0V$	-	-	1	$\mu\text{A}$
$I_{DSS}$	Zero Gate Voltage Drain Current, $T_J=100^\circ\text{C}$		-	-	100	
$V_{GS(\text{th})}$	Gate-Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2.0	2.9	4.0	V
$R_{DS(on)}$	Drain-Source on-Resistance <sup>2</sup>	$V_{GS}=10V, I_D=20A$	-	6.2	7.2	$\text{m}\Omega$
$C_{iss}$	Input Capacitance	$V_{DS}=50V, V_{GS}=0V, f=1\text{MHz}$	-	5240	-	pF
$C_{oss}$	Output Capacitance		-	412	-	
$C_{rss}$	Reverse Transfer Capacitance		-	10	-	
$R_g$	Total Gate Charge	$V_{GS}=0V, V_{DS}=0V, f=1\text{MHz}$	-	1.7	-	$\Omega$
$Q_g$	Total Gate Charge	$V_{GS}=10V, V_{DS}=50V, I_D=20A$	-	18	-	nC
$Q_{gs}$	Gate-Source Charge		-	10	-	
$Q_{gd}$	Gate-Drain Charge		-	72	-	
$t_{a(on)}$	Turn-on Delay Time	$V_{GS}=10V, V_{DS}=50V, R_G=3\Omega, I_D=20A$	-	22	-	ns
$t_r$	Turn-on Rise Time		-	115	-	
$t_{a(off)}$	Turn-off Delay Time		-	44	-	
$t_f$	Turn-off Fall Time		-	105	-	
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$I_F=20A, V_{GS}=0V$	-	-	1.2	V
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0V$ , Force Current	-	-	190	A
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F=20A, dI/dt=100A/\mu\text{s}$	-	110	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge		-	202	-	nC

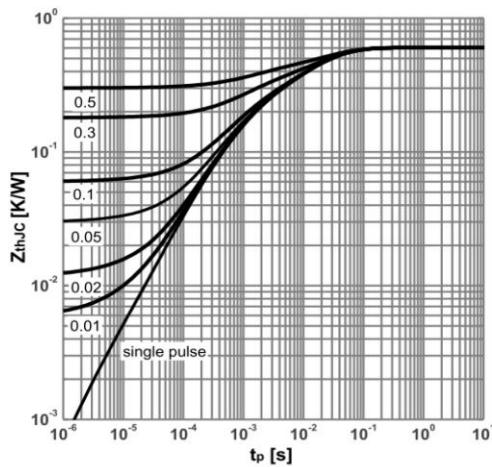
**Notes:**

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leqslant 300\mu\text{s}$  , duty cycle  $\leqslant 2\%$
- 3、The E<sub>AS</sub> data shows Max. rating. The test condition is  $V_{DD}=50V, V_{GS}=10V, L=0.5\text{mH}, I_{AS}=45A$
- 4、The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5、The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

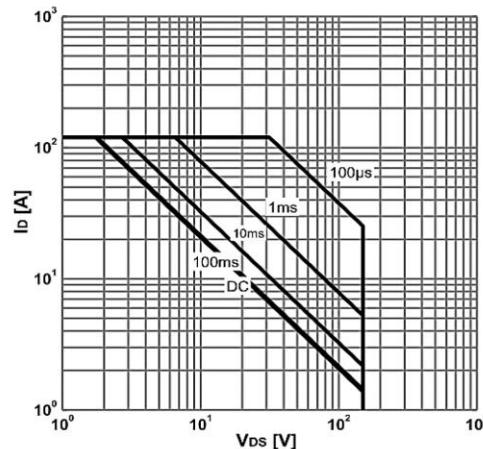
#### 4.Typical Characteristics



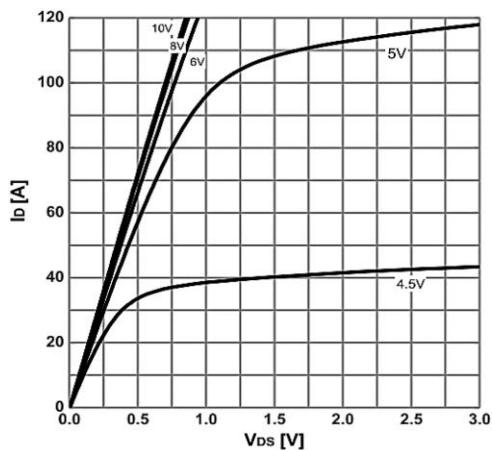
**Figure 1. Power dissipation**



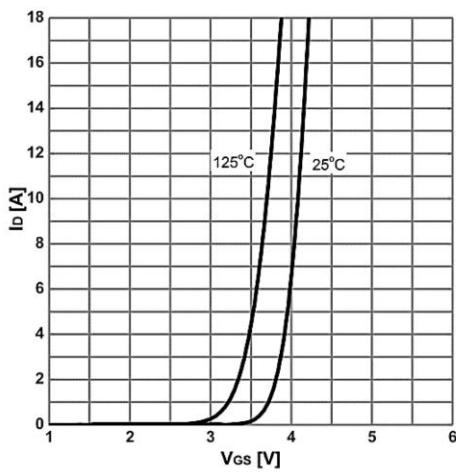
**Figure 2. Max. transient thermal impedance**



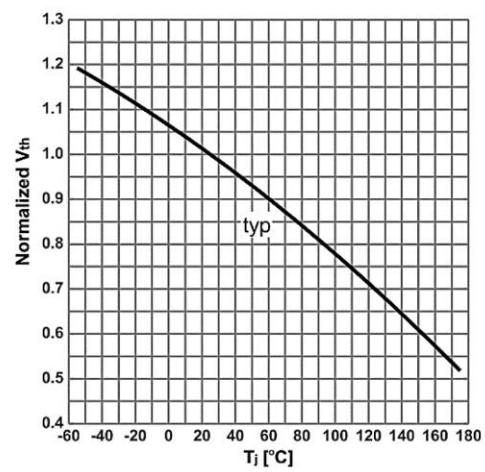
**Figure 3. Safe operating area**



**Figure 4. Typ. output characteristics**



**Figure 5. Typ. transfer characteristics**



**Figure 6. Gate threshold voltage vs. Junction Temperature**

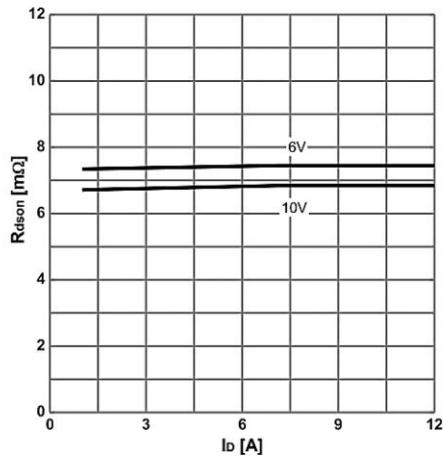


Figure 7. On-state resistance vs. Drain current

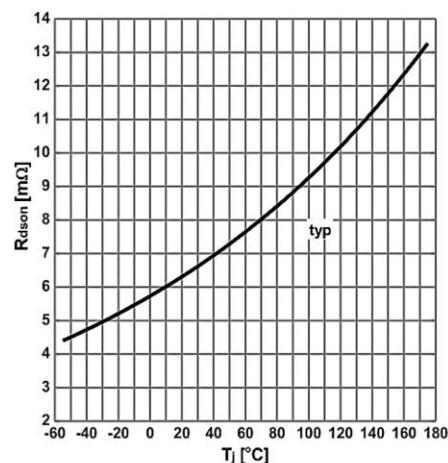


Figure 8. On-state resistance vs. Junction temperature

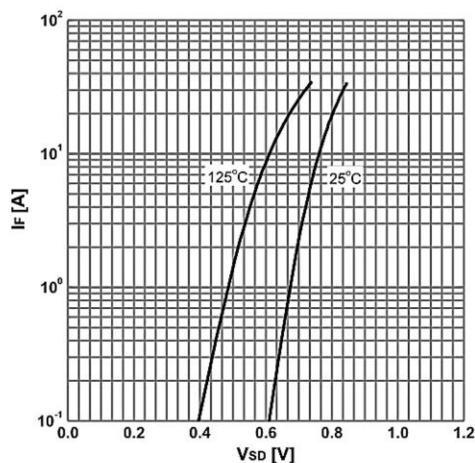


Figure 9. Forward characteristics of reverse diode

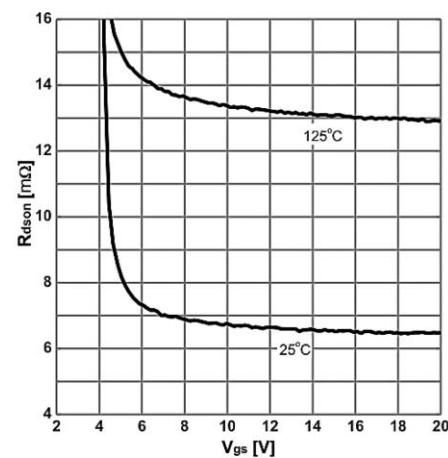


Figure 10. On-state resistance vs.  $V_{gs}$  characteristics

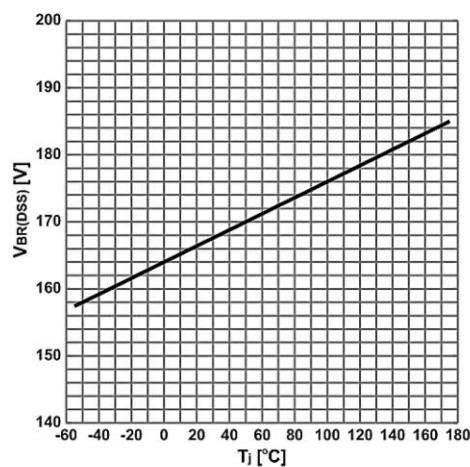


Figure 10: Breakdown Voltage Variation vs. Temperature

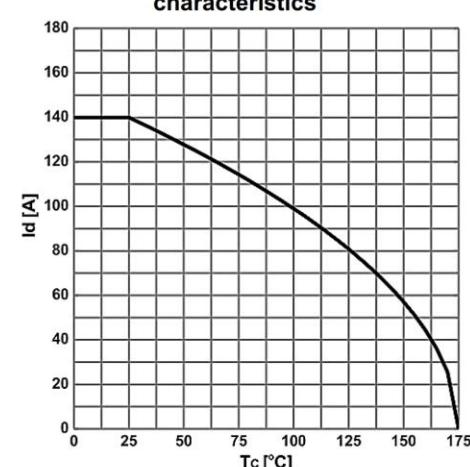
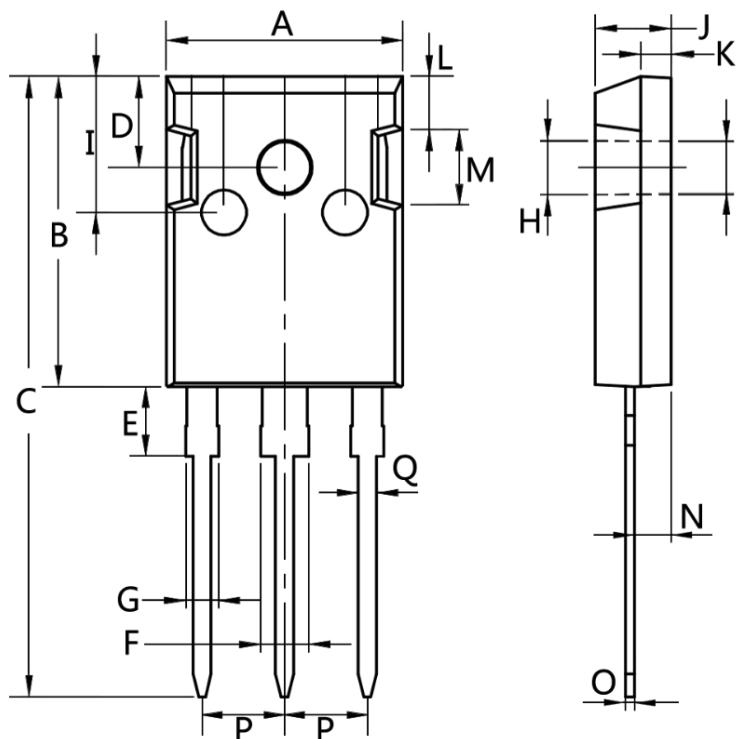


Figure 11: Maximum Drain Current

## 5.Package Mechanical Data

TO-247-3L



Dim.	Min.	Max.
A	15.0	16.0
B	20.0	21.0
C	41.0	42.0
D	5.0	6.0
E	4.0	5.0
F	2.5	3.5
G	1.75	2.5
H	3.0	3.5
I	8.0	10.0
J	4.9	5.1
K	1.9	2.1
L	3.5	4.0
M	4.75	5.25
N	2.0	3.0
O	0.55	0.75
P	Type 5.08	
Q	1.2	1.3